

HEF40175B

Quad D-type flip-flop

Rev. 7 — 3 May 2011

Product data sheet

1. General description

The HEF40175B is a quad edge-triggered D-type flip-flop with four data inputs (D0 to D3), a clock input (CP), an overriding asynchronous master reset input ($\overline{\text{MR}}$), four buffered outputs (Q0 to Q3), and four complementary buffered outputs ($\overline{\text{Q0}}$ to $\overline{\text{Q3}}$). Information on D0 to D3 is transferred to Q0 to Q3 on the LOW-to-HIGH transition of CP if $\overline{\text{MR}}$ is HIGH. When LOW, $\overline{\text{MR}}$ resets all flip-flops (Q0 to Q3 = LOW; $\overline{\text{Q0}}$ to $\overline{\text{Q3}}$ = HIGH), independent of CP and D0 to D3.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD} , V_{SS} , or another input.

The device is suitable for use over both the industrial (−40 °C to +85 °C) and automotive (−40 °C to +125 °C) temperature ranges.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Operates across the automotive temperature range from −40 °C to +125 °C
- Complies with JEDEC standard JESD 13-B

3. Applications

- Industrial
- Shift registers
- Buffer/storage register
- Pattern generator

4. Ordering information

Table 1. Ordering information

All types operate from −40 °C to +125 °C.

Type number	Package		Version
	Name	Description	
HEF40175BP	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
HEF40175BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
HEF40175BTT	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1



5. Functional diagram

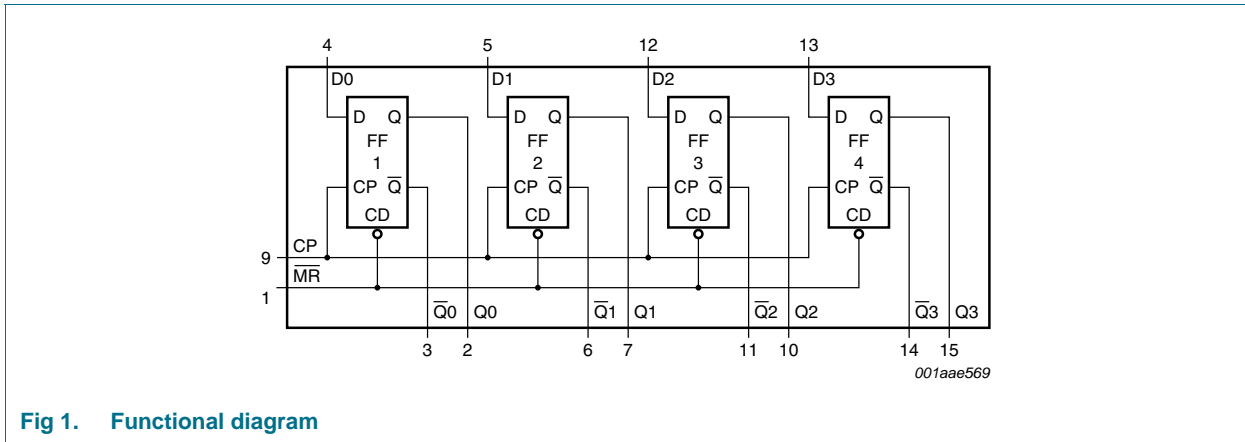


Fig 1. Functional diagram

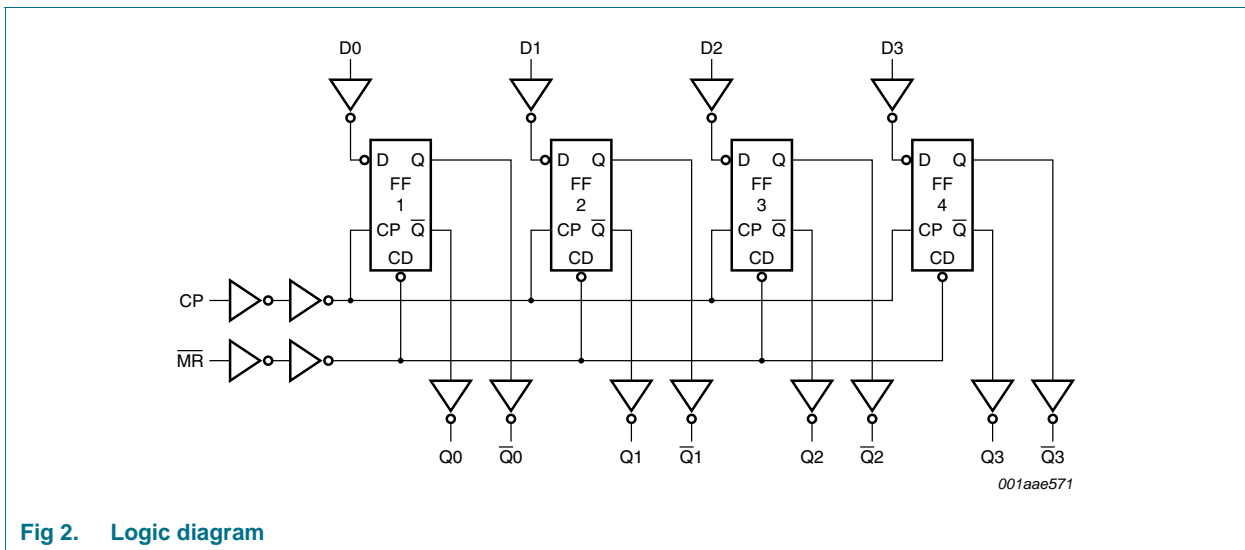
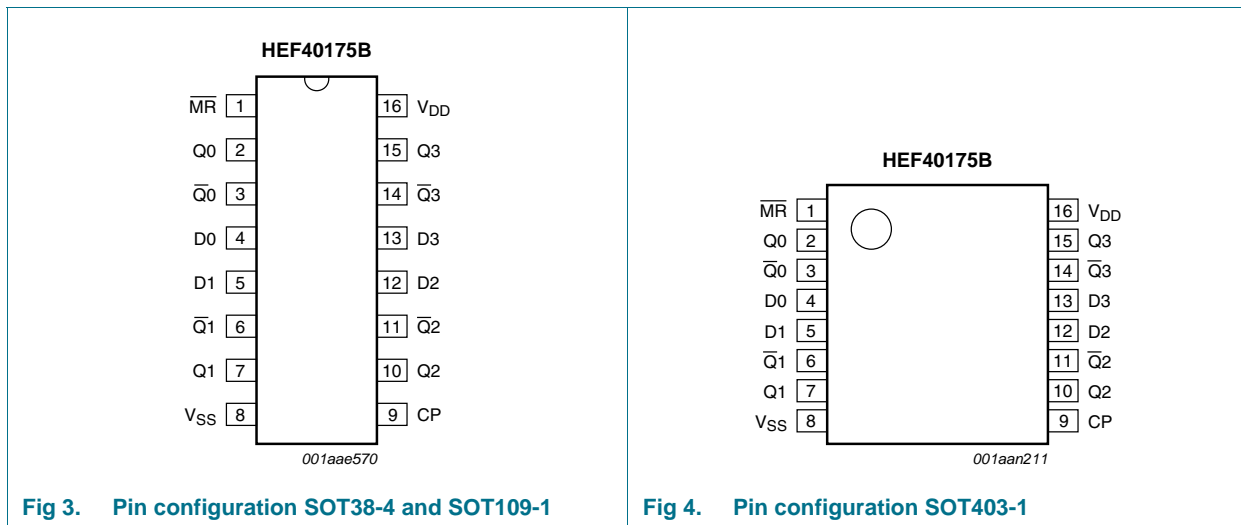


Fig 2. Logic diagram

6. Pinning information

6.1 Pinning



6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{\text{MR}}$	1	master reset input (active LOW)
Q0 to Q3	2, 7, 10, 15	buffered output
$\overline{\text{Q}}0$ to $\overline{\text{Q}}3$	3, 6, 11, 14	complementary buffered output
D0 to D3	4, 5, 12, 13	data input
V _{SS}	8	ground supply voltage
CP	9	clock input (LOW-to-HIGH edge-triggered)
V _{DD}	16	supply voltage

7. Functional description

Table 3. Function table [1]

Input			Output	
CP	Dn	$\overline{\text{MR}}$	Qn	$\overline{\text{Q}}n$
↑	H	H	H	L
↑	L	H	L	H
↓	X	H	no change	no change
X	X	L	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; ↑ = positive-going transition; ↓ = negative-going transition.

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		-0.5	+18	V
I_{IK}	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{DD} + 0.5\text{ V}$	-	± 10	mA
V_I	input voltage		-0.5	$V_{DD} + 0.5$	V
I_{OK}	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{DD} + 0.5\text{ V}$	-	± 10	mA
$I_{I/O}$	input/output current		-	± 10	mA
I_{DD}	supply current		-	50	mA
T_{stg}	storage temperature		-65	+150	°C
T_{amb}	ambient temperature		-40	+125	°C
P_{tot}	total power dissipation	$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$			
		DIP16 package	[1] -	750	mW
		SO16 package	[2] -	500	mW
		TSSOP16 package	[3] -	500	mW
P	power dissipation	per output	-	100	mW

[1] For DIP16 package: P_{tot} derates linearly with 12 mW/K above 70 °C.

[2] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

[3] For TSSOP16 package: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	supply voltage		3	-	15	V
V_I	input voltage		0	-	V_{DD}	V
T_{amb}	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5\text{ V}$	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10\text{ V}$	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15\text{ V}$	-	-	0.08	$\mu\text{s/V}$

10. Static characteristics

Table 6. Static characteristics
 $V_{SS} = 0\text{ V}$; $V_I = V_{SS}$ or V_{DD} ; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	$T_{amb} = -40\text{ }^{\circ}\text{C}$		$T_{amb} = +25\text{ }^{\circ}\text{C}$		$T_{amb} = +85\text{ }^{\circ}\text{C}$		$T_{amb} = +125\text{ }^{\circ}\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
V_{IL}	LOW-level input voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V
V_{OH}	HIGH-level output voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
V_{OL}	LOW-level output voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
I_{OH}	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mA
I_{OL}	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mA
I_I	input leakage current		15 V	-	± 0.1	-	± 0.1	-	± 1.0	-	± 1.0	μA
I_{DD}	supply current	all valid input combinations; $ I_O = 0\text{ A}$	5 V	-	1.0	-	1.0	-	30	-	30	μA
			10 V	-	2.0	-	2.0	-	60	-	60	μA
			15 V	-	4.0	-	4.0	-	120	-	120	μA
C_I	input capacitance		-	-	-	7.5	-	-	-	-	pF	

11. Dynamic characteristics

Table 7. Dynamic characteristics
 $V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$; for test circuit see [Figure 6](#); unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula	Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	CP to Qn or \overline{Qn} ; see Figure 5	5 V	$53\text{ ns} + (0.55\text{ ns/pF}) C_L$	-	80	160	ns
			10 V	$24\text{ ns} + (0.23\text{ ns/pF}) C_L$	-	35	70	ns
			15 V	$17\text{ ns} + (0.16\text{ ns/pF}) C_L$	-	25	50	ns
		\overline{MR} to Qn; see Figure 5	5 V	$48\text{ ns} + (0.55\text{ ns/pF}) C_L$	-	75	155	ns
			10 V	$19\text{ ns} + (0.23\text{ ns/pF}) C_L$	-	30	65	ns
			15 V	$17\text{ ns} + (0.16\text{ ns/pF}) C_L$	-	25	50	ns

Table 7. Dynamic characteristics ...continued

$V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ °C}$; for test circuit see [Figure 6](#); unless otherwise specified.

Symbol	Parameter	Conditions	V _{DD}	Extrapolation formula	Min	Typ	Max	Unit
t _{PLH}	LOW to HIGH propagation delay	CP to Qn or \overline{Qn} ; see Figure 5	5 V	$43\text{ ns} + (0.55\text{ ns/pF}) C_L$	-	70	140	ns
			10 V	$19\text{ ns} + (0.23\text{ ns/pF}) C_L$	-	30	65	ns
			15 V	$17\text{ ns} + (0.16\text{ ns/pF}) C_L$	-	25	45	ns
		\overline{MR} to \overline{Qn} ; see Figure 5	5 V	$43\text{ ns} + (0.55\text{ ns/pF}) C_L$	-	70	140	ns
			10 V	$19\text{ ns} + (0.23\text{ ns/pF}) C_L$	-	30	65	ns
			15 V	$17\text{ ns} + (0.16\text{ ns/pF}) C_L$	-	25	50	ns
t _t	transition time	see Figure 5	5 V	$10\text{ ns} + (1.00\text{ ns/pF}) C_L$	-	60	120	ns
			10 V	$9\text{ ns} + (0.42\text{ ns/pF}) C_L$	-	30	60	ns
			15 V	$6\text{ ns} + (0.28\text{ ns/pF}) C_L$	-	20	40	ns
t _{su}	set-up time	Dn to CP; see Figure 5	5 V		60	30	-	ns
			10 V		20	10	-	ns
			15 V		15	5	-	ns
t _h	hold time	Dn to CP; see Figure 5	5 V		+25	-5	-	ns
			10 V		10	0	-	ns
			15 V		10	0	-	ns
t _w	pulse width;	CP input LOW; minimum pulse width see Figure 5	5 V		90	45	-	ns
			10 V		35	15	-	ns
			15 V		25	10	-	ns
		\overline{MR} input LOW; minimum pulse width see Figure 5	5 V		80	40	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
t _{rec}	recovery time	\overline{MR} input; see Figure 5	5 V		0	-30	-	ns
			10 V		0	-20	-	ns
			15 V		0	-15	-	ns
f _{max}	maximum frequency		5 V		5	11	-	MHz
			10 V		15	30	-	MHz
			15 V		20	45	-	MHz

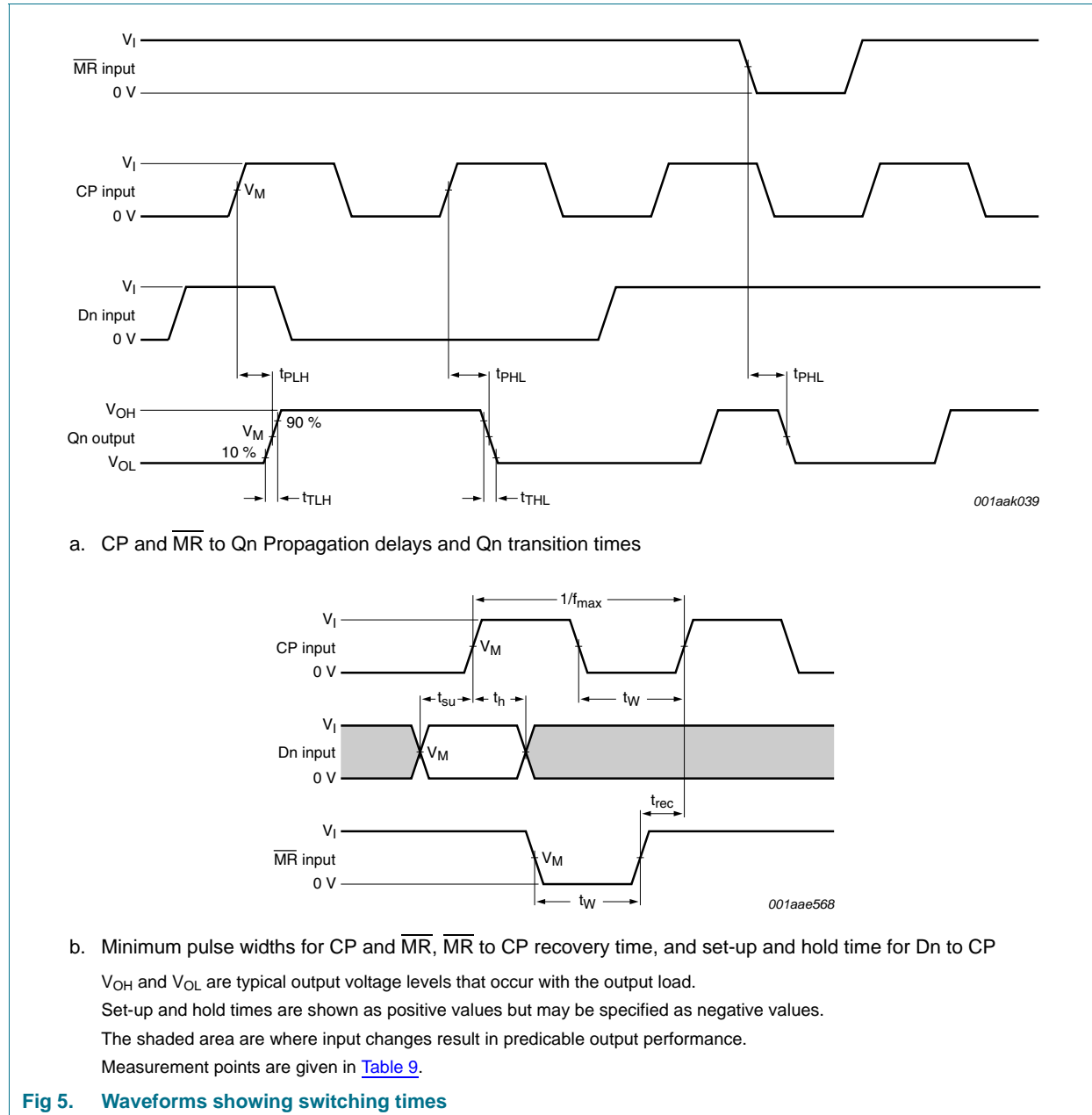
[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formula shown (C_L in pF).

Table 8. Dynamic power dissipation P_D

P_D can be calculated from the formulas shown. $V_{SS} = 0\text{ V}$; $t_r = t_f \leq 20\text{ ns}$; $T_{amb} = 25\text{ °C}$.

Symbol	Parameter	V _{DD}	Typical formula for P _D (μW)	where:
P _D	dynamic power dissipation	5 V	$P_D = 2000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f _i = input frequency in MHz,
		10 V	$P_D = 8400 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f _o = output frequency in MHz,
		15 V	$P_D = 22500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	C _L = output load capacitance in pF, V _{DD} = supply voltage in V, Σ(f _o × C _L) = sum of the outputs.

12. Waveforms



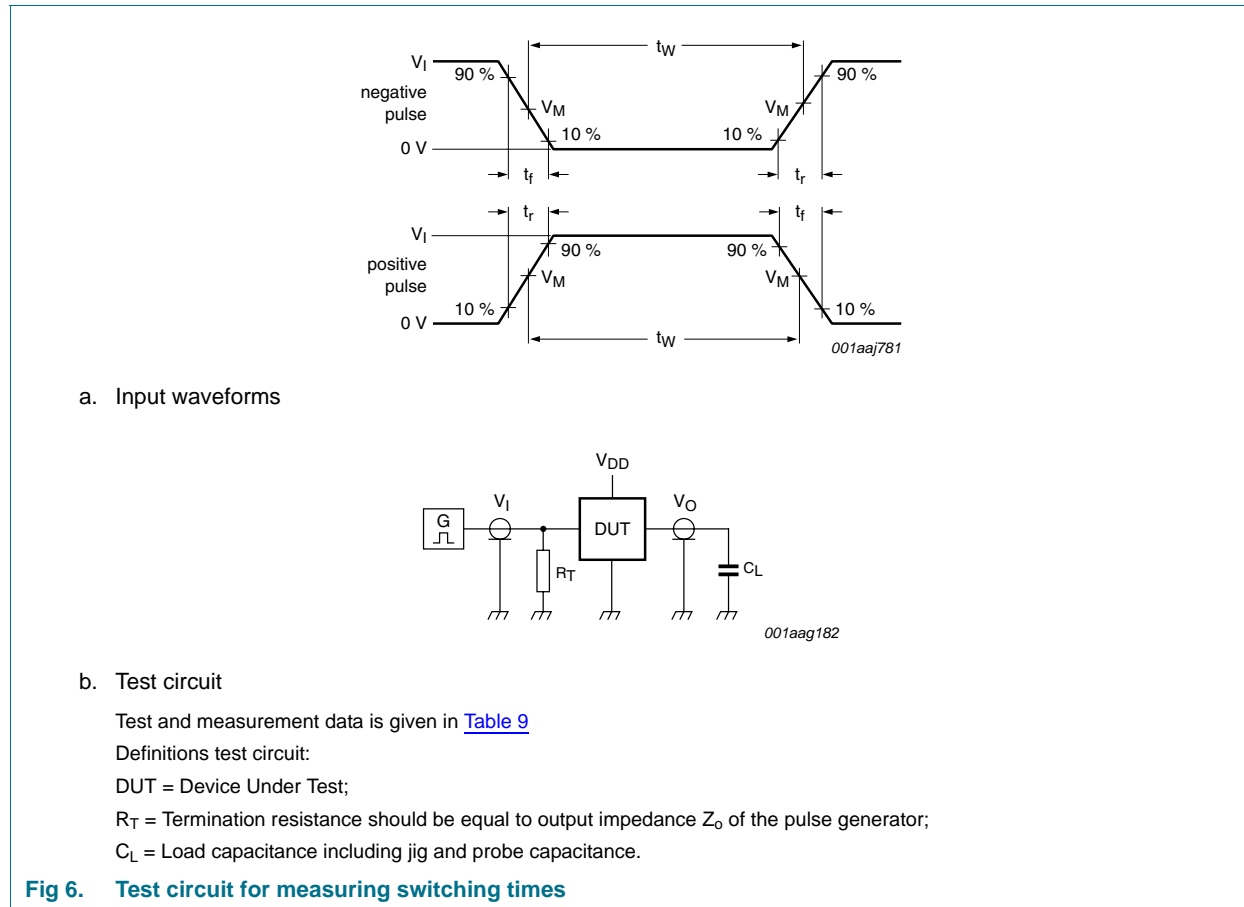


Table 9. Measurement points and test data

Supply voltage	Input		Load
V_{DD}	V_I	t_r, t_f	C_L
5 V to 15 V	V_{SS} or V_{DD}	≤ 20 ns	50 pF

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

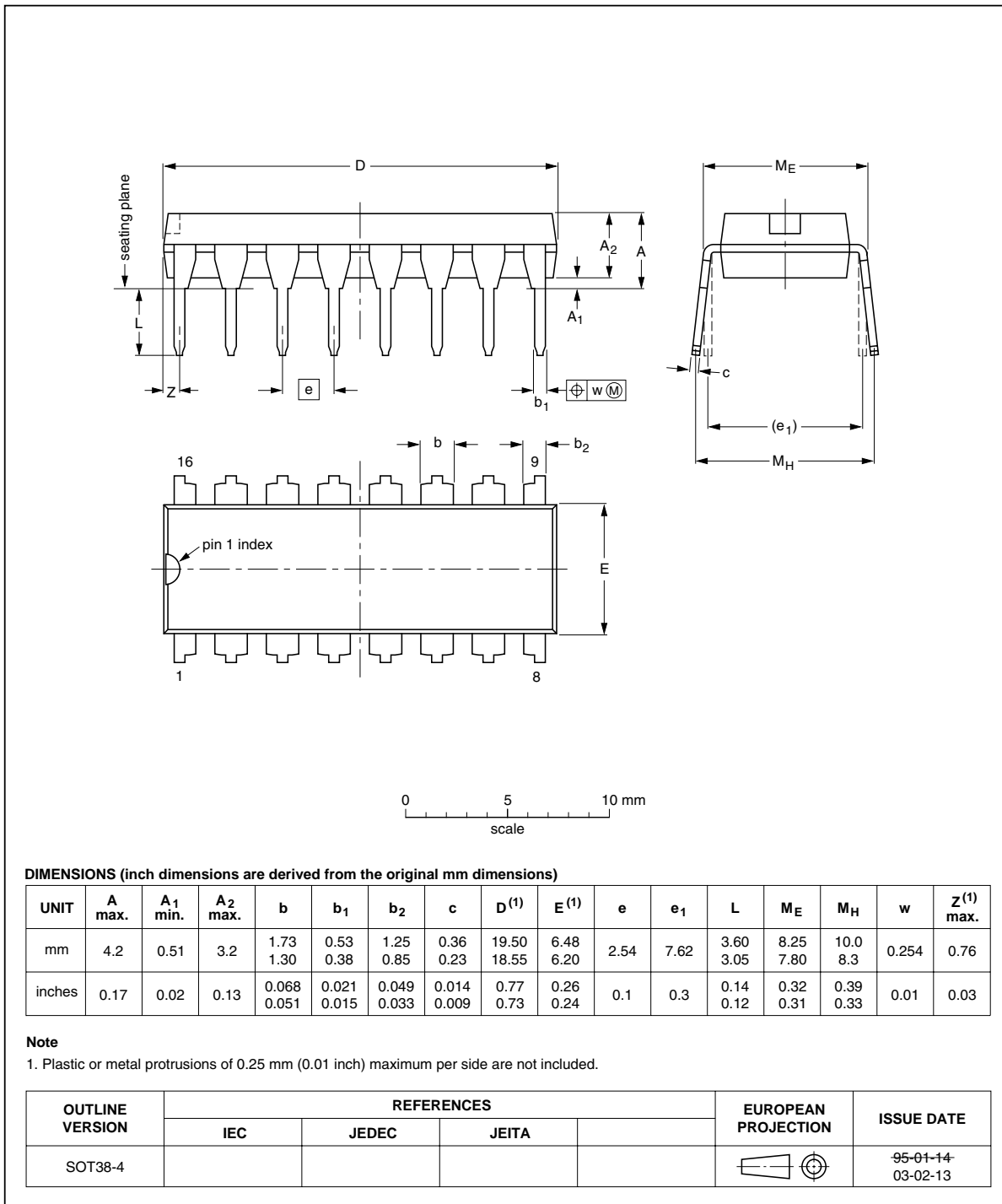


Fig 7. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

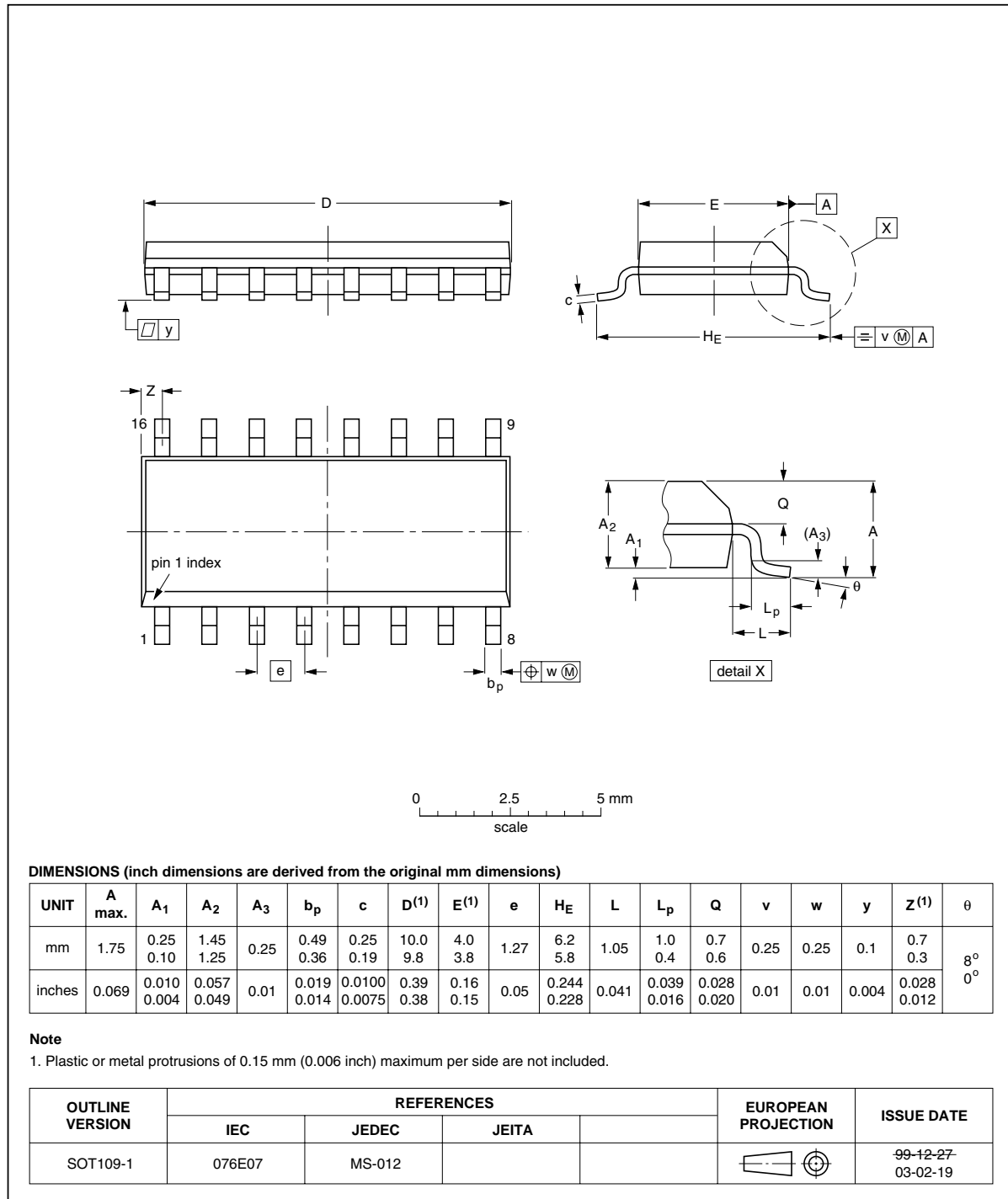


Fig 8. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

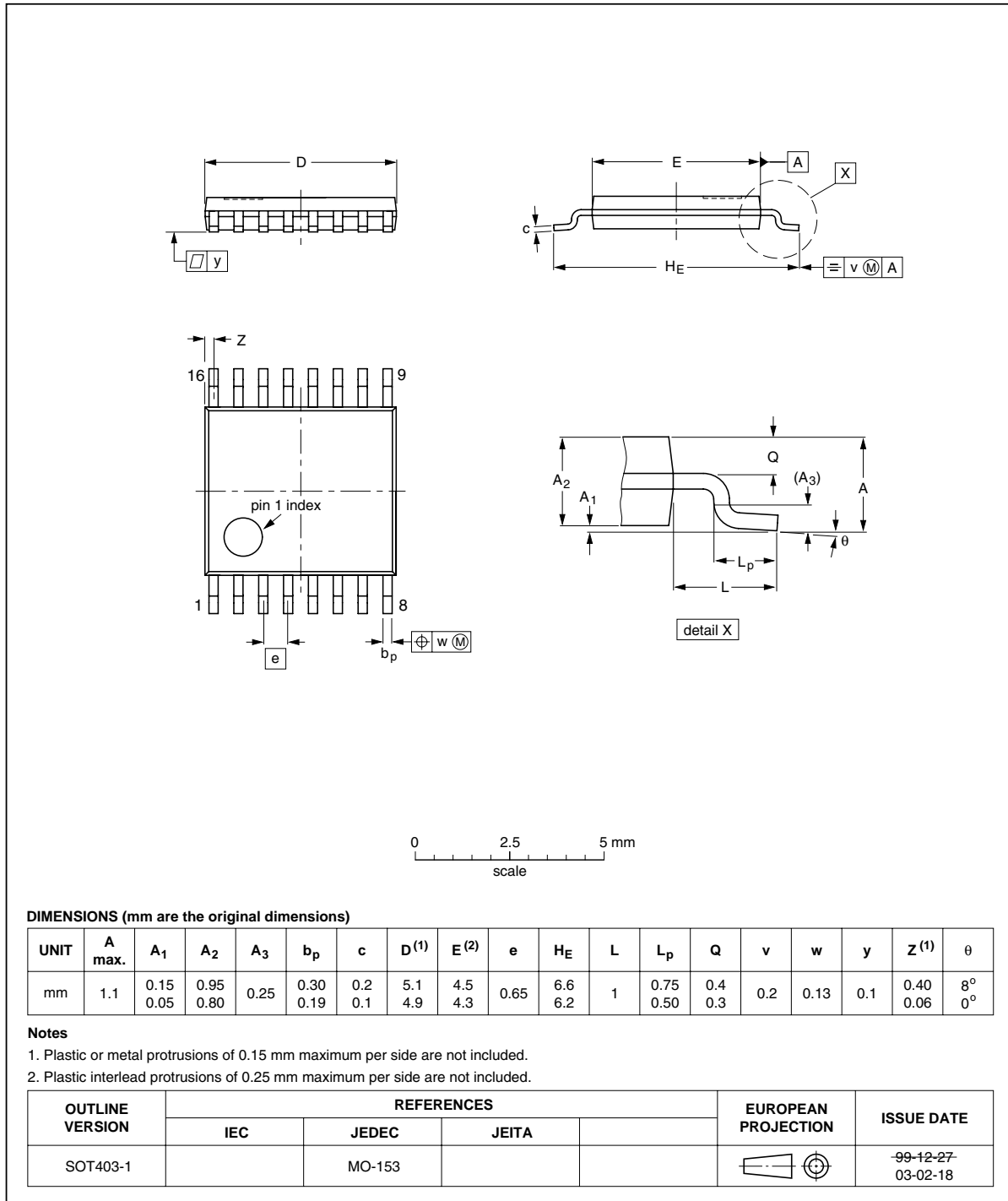


Fig 9. Package outline SOT403-1 (TSSOP16)

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF40175B v.7	20110503	Product data sheet	-	HEF40175B v.6
Modifications:	• Temperature range (maximum) increased from 85 °C to 125 °C throughout the data sheet.			
HEF40175B v.6	20101214	Product data sheet	-	HEF40175B v.5
HEF40175B v.5	20100105	Product data sheet	-	HEF40175B v.4
HEF40175B v.4	20090813	Product data sheet	-	HEF40175B_CNV v.3
HEF40175B_CNV v.3	19950101	Product specification	-	HEF40175B_CNV v.2
HEF40175B_CNV v.2	19950101	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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